

Amendments to the Specification

**Kindly amend the paragraph beginning on page 13, line 19 as follows:**

Regarding the ~~cleaning~~ timing of the cleaning of ~~for~~ the inner wall 21 of the cleaning cup 20 and the inner wall 31 of the cleaning vessel 30, it is only essential to perform the inner wall cleaning process when the chemical liquid is not supplied. Usually, the inner wall cleaning process is carried out at the same time as the semiconductor substrate W is rinsed, as stated above. However, it is desirable that the supply of the rinsing liquid to the semiconductor substrate W from the cleaning device 50 should be continued for a while even after the spray of the cleaning liquid onto the cleaning cup 20 and the cleaning vessel 30 has been stopped in order that the cleaning liquid sprayed onto the cleaning cup 20 and the cleaning vessel 30 and included with the by-product does not adhere to the semiconductor substrate W and ~~being-become~~ dried thereon. It is also possible to clean the inner wall 21 of the cleaning cup 20 and the inner wall 31 of the cleaning vessel 30 when no semiconductor substrate W is present in the cleaning cup 20.

**Kindly amend the paragraph beginning on page 13, line 19 as follows:**

Fig. 5 is a diagram showing the surface condition of the semiconductor substrate W taken out of the cleaning apparatus 1 after being cleaned and dried as stated above. Fig. 6 is a diagram showing the surface condition of the semiconductor substrate W taken out of the cleaning apparatus 1 after being cleaned with only the cleaning devices 40 and 50 without using the cleaning devices 70 and 80. In the two figures, black dots indicate reverse contamination (defects). It will be understood

from these figures that reverse contamination is ~~extremely prevented-effectively prevented~~ by cleaning the inner wall 21 of the cleaning cup 20 and the inner wall 31 of the cleaning vessel 30 with the cleaning devices 70 and 80.

**Kindly amend the paragraph beginning on page 13, line 19 as follows:**

Regarding the cleaning timing for the supporting device 10, it is only essential to perform the supporting device cleaning process when the chemical liquid is not supplied. Usually, the supporting device cleaning process is carried out at the same time as the rinsing of the semiconductor substrate W ~~is rinsed~~, as stated above. However, it is desirable that the supply of the rinsing liquid to the semiconductor substrate W from the cleaning device 50 should be continued for a while even after the spray of the cleaning liquid onto the supporting device 10 has been stopped in order that the cleaning liquid sprayed onto the supporting device 10 and included with the by-product does not ~~adhered-adhere~~ to the semiconductor substrate W and ~~being-become~~ dried thereon. It is also possible to clean the supporting device 10 when no semiconductor substrate W is present in the cleaning cup 20.